C2 Series

Heat Sink for TO-247 and Similar Packages

Ohmite introduces another C series style, called C2 series heat sink (Pat. Pending). This series offers very easy devices assembly with no tool and fixture needed. This powerful heat sink has lower profile, larger surface areas and configurable heat sinks with slide-in clip for TO-247 and compatible packages, etc. and can be thru-hole soldered onto PCBs. It is the ideal type of heat sink for small size, light weight, compact (1U or 2U) electronic packaging with forced or natural convection cooling.

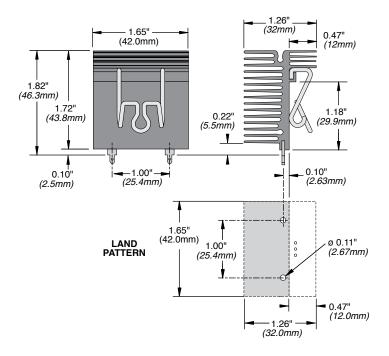


SERIES SPECIFICATIONS

Heatsink Part Number	Surface Area (in² / mm²)	Weight (oz / g)	Length L (mm)	Thermal resistance*
C2A-XT4-46E	45.6 / 29,439	1.8 / 51	1.65 / 42.0	2.8
C2V-XT4-46E				3.2

^{*}Thermal resistance based on fin direction as well as gravity.

DIMENSIONS



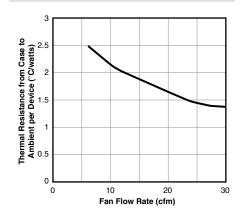
HOW TO ORDER

$$\underbrace{C~2~V~-~X~T~4~-~\underbrace{4~6~E}_{\substack{L \text{ength} \\ V = \text{ degreased}}} E_{\text{RoHS compliant}}$$

CHARACTERISTICS

Heat Sink	AL6063-T5
Spring Clip	Music Wire, Per ASTM A228 with bright nickel plating
Solder Foot	Steel or brass with pure tin plated. RoHS compliant
Surface Finish	Black anodized or degreased
Compatibility	Compatible with parts/ devices: TEH100, TEH140, TO-247

Heat Dissipation



Notes 1) Power dissipation is 40W, single device

- 2) Heat load area as TO-247, metal
- 3) Use no thermal interface material
- 4) Un-ducted air flow